CT2501 Series

Low Dark Current 4-Pin Phototransistor Optocoupler

Features

- High isolation 5000 VRMS
- CTR flexibility available see order information
- DC input with transistor output
- Operating temperature range 55 °C to 110 °C
- Regulatory Approvals
 - UL UL1577 (E364000)
 - VDE EN60747-5-5(VDE0884-5)
 - CQC GB4943.1, GB8898
 - IEC60065, IEC60950

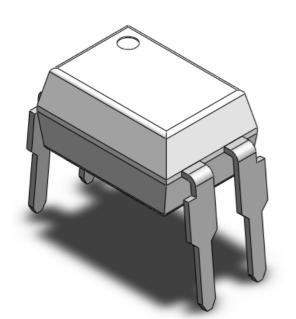
Applications

- Switch mode power supplies
- Computer peripheral interface
- Microprocessor system interface

Description

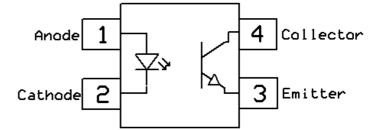
The CT2501 series consists of a phototransistor optically coupled to a gallium arsenide Infrared-emitting diode in a 4-lead DIP package with different lead forming options.

Package Outline



Note: Different lead forming options available. See package

dimension.



Schematic



Low Dark Current 4-Pin Phototransistor Optocoupler

Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage	5000	VRMS	
Topr	Operating temperature	-55 ~ +110	°C	
Тѕтс	Storage temperature	-55 ~ +150	°C	
Tsol	Soldering temperature	260	°C	
Emitter				
lF	Forward current	80	mA	
IF(TRANS)	Peak transient current (≤1µs P.W,300pps)	1	А	
VR	Reverse voltage	6	V	
PD	Emitter power dissipation	150	mW	
Detector				
Pc	Detector power dissipation	150	mW	
BVCEO	Collector-Emitter Breakdown Voltage	80	V	
BVECO	Emitter-Collector Breakdown Voltage	7	V	
lc	Collector Current	50	mA	



Electrical Characteristics *T_A* = 25 °C (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I _F =10mA		1.2	1.4	V	
IR	Reverse Current	$V_{R} = 6V$	-	-	5	μA	
CIN	Input Capacitance	f= 1MHz	-	30	-	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
BVCEO	Collector-Emitter Breakdown	Ic= 100μA	80	-	-	V	
BVECO	Emitter-Collector Breakdown	I _E = 100μA	7	-	-	V	
ICEO	Collector-Emitter Dark Current	V _{CE} = 80V, I _F =0mA	-	-	100	nA	

Transfer Characteristics

Symbol	Parameters		Test Conditions	Min	Тур	Max	Units	Notes
	CT2501 CT2501K CT2501L		80		400	-		
			300		600			
		CT2501L	- I⊧= 5mA, Vcε= 5V -	200		400	~ %	
стр	Current Transfer	CT2501M		80		240		
CTR	Ratio	CT2501D		100		300		
		CT2501H		80		160		
		CT2501W		130		260		
		CT2501Q		100		200		
Mariaur	Collector-Emitter Satur	ation	1- 20mA la 1mA		0.1	0.2	V	
VCE(SAT)	Voltage		I⊧= 20mA, Ic= 1mA	-	0.1	0.2	v	
RIO	Isolation Resistance		V _{IO} = 1kV _{DC}	10 ¹¹			Ω	
Cio	Isolation Capacitance		f= 1MHz		0.5	1	pF	

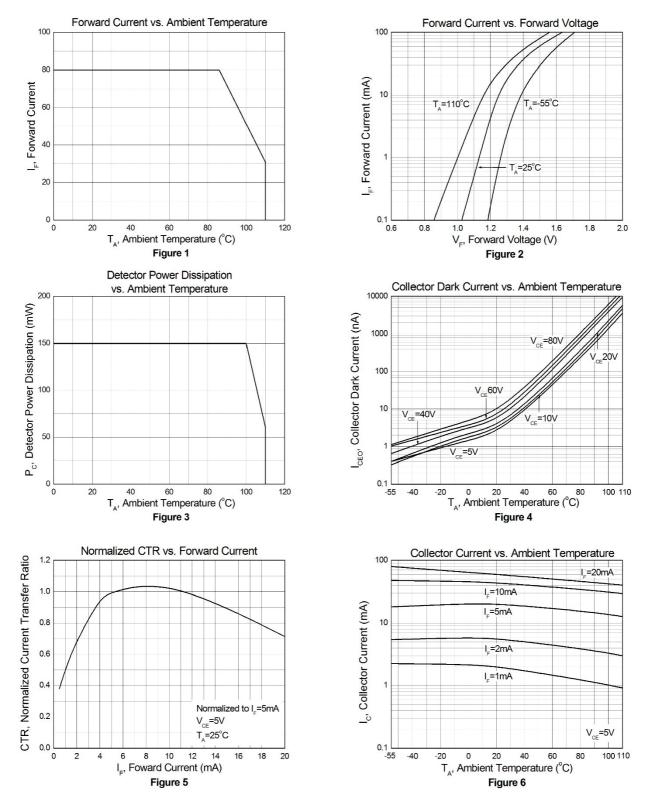
Switching Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
tr	Rise Time	V _{CC} = 10V, I _C = 2mA,	-	3	-		
tr	Fall Time	R _L = 100Ω	-	5	-	μs	



Low Dark Current 4-Pin Phototransistor Optocoupler

Typical Characteristic Curves





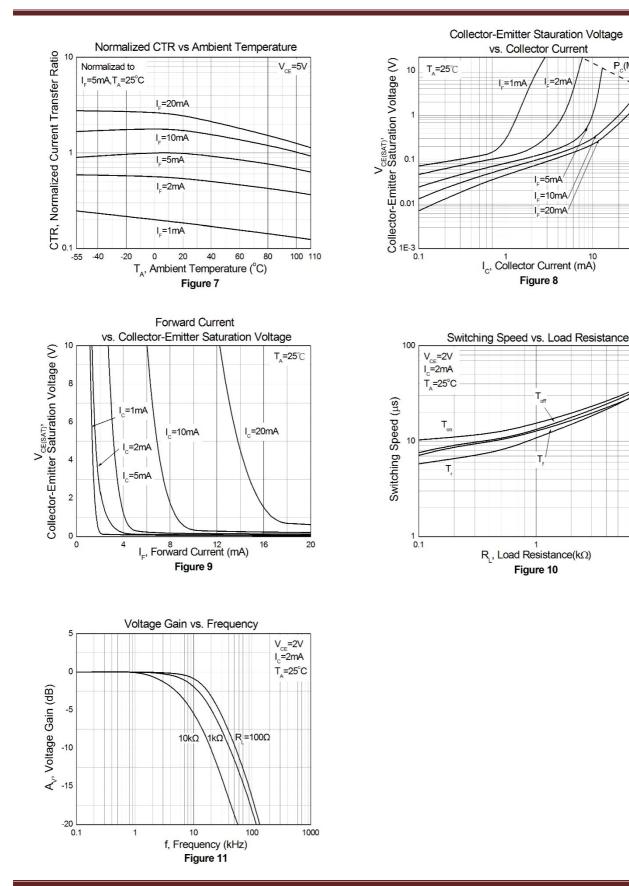
CT2501 Series

P_c(MAX.)

50

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Low Dark Current 4-Pin Phototransistor Optocoupler





CT2501 Series Low Dark Current 4-Pin Phototransistor Optocoupler

Test Circuit

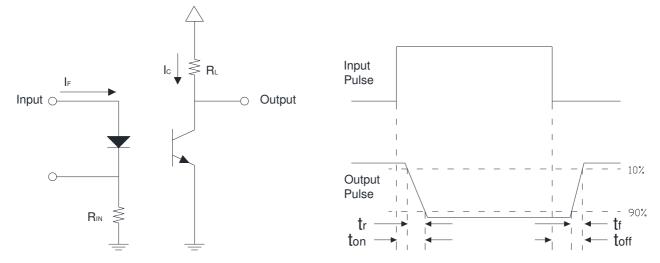
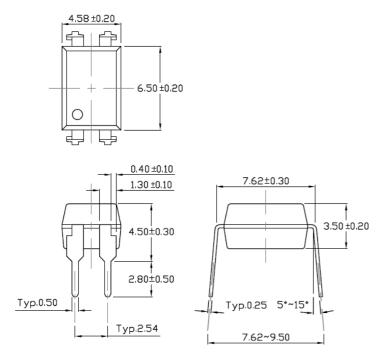


Figure 12: Switching Time Test Circuits

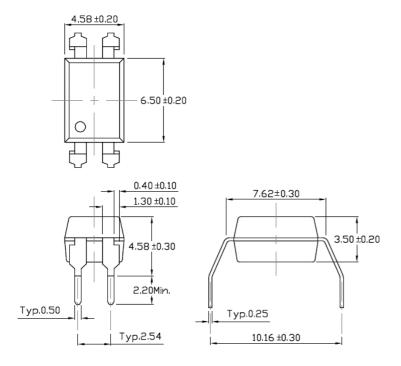


Package Dimension Dimensions in mm unless otherwise stated

Standard DIP – Through Hole

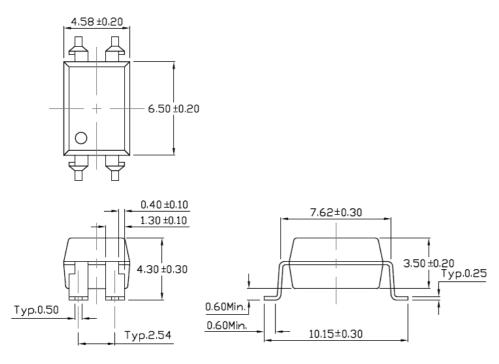


Gullwing (400mil) Lead Forming – Through Hole (M Type)

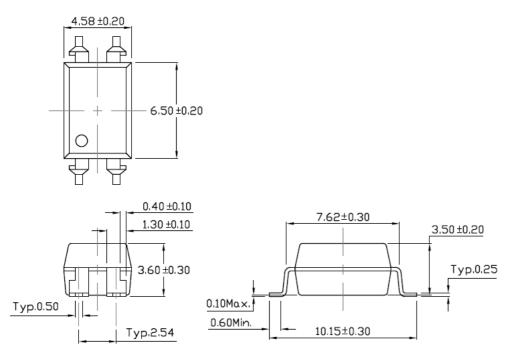




Surface Mount Lead Forming (S Type)

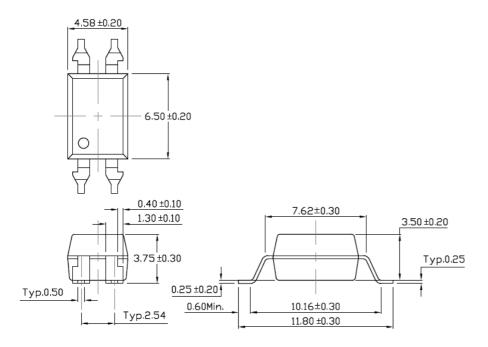


Surface Mount (Low Profile) Lead Forming (SL Type)





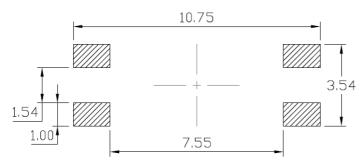
Surface Mount (Gullwing) Lead Forming (SLM Type)



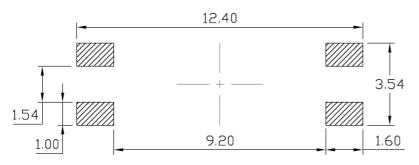


Recommended Solder Mask Dimensions in mm unless otherwise stated

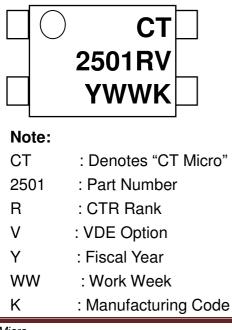
Surface Mount Lead Forming & Surface Mount (Low Profile) Lead Forming



Surface Mount (Gullwing) Lead Forming



Marking Information





Ordering Information

CT2501X(V)(Y)(Z)-HG

X = Part No. (X=L,M,D,H,W, None)

V = VDE Option (V or None)

Y = Lead form option (S, SL, M, SLM or none)

Z = Tape and reel option (T1, T2, T3, T4 or none)

H = Lead frame option (H: Iron, None: Copper)

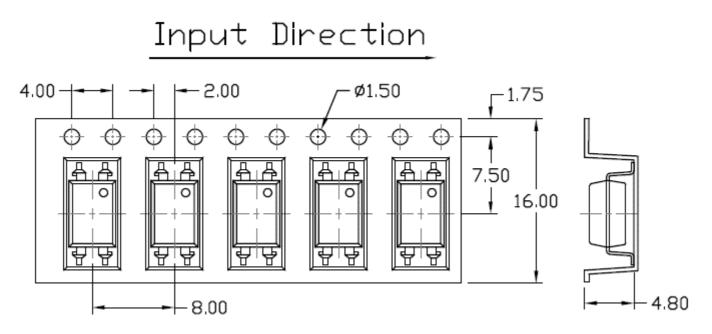
G= Material option (G: Green, None: Non-green)

Option	Description	Quantity
None	Standard 4 Pin DIP	100 Units/Tube
М	Gullwing (400mil) Lead Forming	100 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1500 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1500 Units/Reel
S(T3)	Surface Mount Lead Forming – With Option 3 Taping	1000 Units/Reel
S(T4)	Surface Mount Lead Forming – With Option 4 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming- With Option 1 Taping	1500 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1500 Units/Reel
SL(T3)	Surface Mount (Low Profile) Lead Forming- With Option 3 Taping	1000 Units/Reel
SL(T4)	Surface Mount (Low Profile) Lead Forming – With Option 4 Taping	1000 Units/Reel
SLM(T1)	Surface Mount (Gullwing) Lead Forming- With Option 1 Taping	1500 Units/Reel
SLM(T2)	Surface Mount (Gullwing) Lead Forming – With Option 2 Taping	1500 Units/Reel

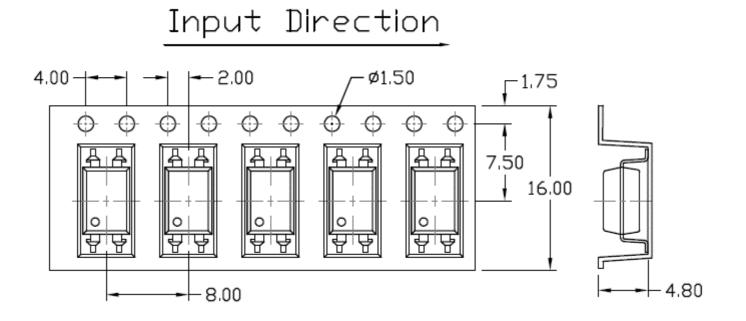


Carrier Tape Specifications Dimensions in mm unless otherwise stated

Option S(T1) & SL(T1)

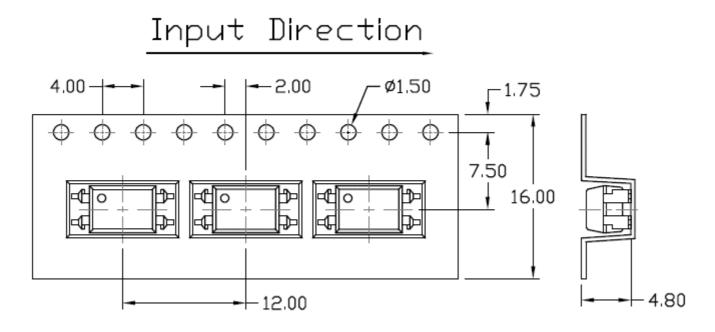


Option S(T2) & SL(T2)

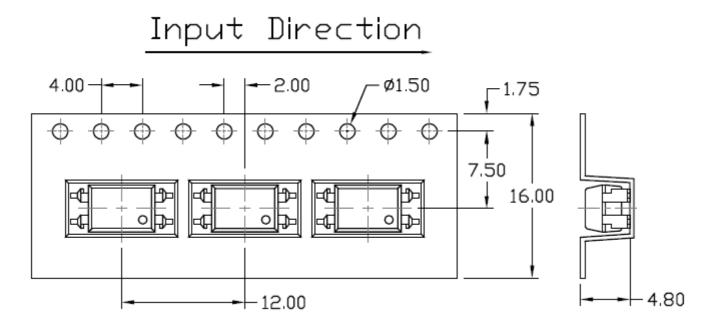




Option S(T3) & SL(T3)

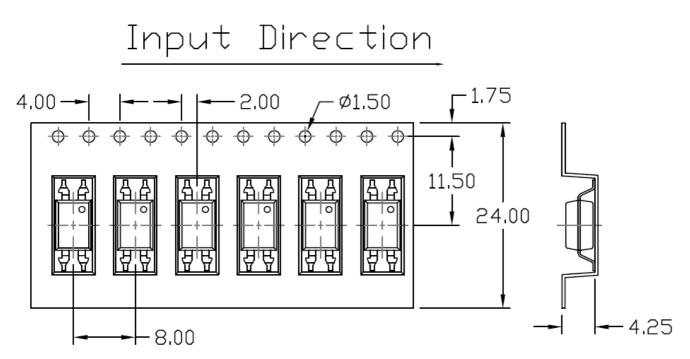


Option S(T4) & SL(T4)

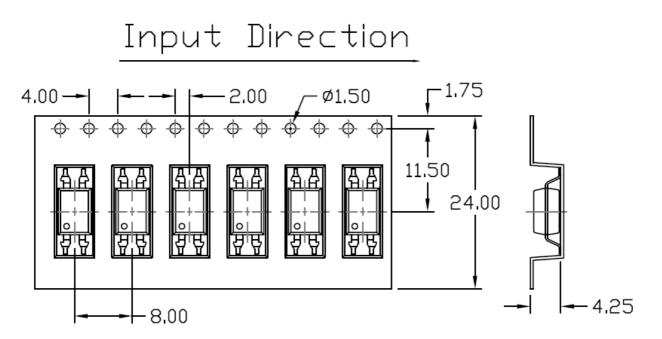




Option SLM(T1)

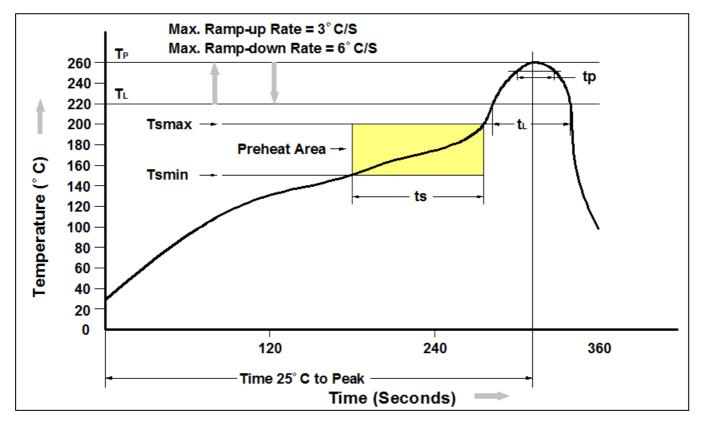


Option SLM(T2)





Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150 <i>°</i> C
Temperature Max. (Tsmax)	200 <i>°</i> C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t_L to t_P)	3℃/second max.
Liquidous Temperature (TL)	217 <i>°</i> C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260 ℃ +0 ℃ / -5 ℃
Time (t _P) within 5 ℃ of 260 ℃	30 seconds
Ramp-down Rate $(T_P \text{ to } T_L)$	6°C/second max
Time 25℃ to Peak Temperature	8 minutes max.



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